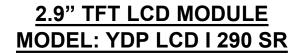
# **PRODUCT SPECIFICATION**





- < >> Preliminary Specification
- < ◆> Finally Specification

	CUSTOMER'	S APPROVAL
CUSTOMER:		
SIG	NATURE:	DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
TFT S. G. H 20220824			TFT Z. Y. J 20220824

knitter-switch

# **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2022.08.24	ZYJ	Initial Release	

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## 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

## 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	2.9"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normal Black	
Resolution	376 RGB x 960	Pixels
View Direction	Full viewing	Best Image
Module Outline	31.2(H) x 76.6(V) x 2.05(T) (Note1)	mm
Active Area	26.51(H) x 67.68(V)	mm
Pixel Pitch	70.5(H) x 70.5(V)	um
Pixel Arrangement	RGB Vertical stripe	
Polarizer Surface Treatment	Glare	
Display Colors	65K	
Interface	3 wire SPI + 16bit RGB	
Driver IC	ST7701SI-G5	
With or without the touch panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	29	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

## 3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCI	-0.3	4.6	V
Supply Voltage	IOVCC	-0.3	4.6	V
Storage temperature	T <sub>STG</sub>	-30	+80	°C
Operating temperature	T <sub>OP</sub>	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

## 4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage	VCI	2.5	3.3	3.6	V
Supply Voltage	IOVCC	1.65	1.8	3.6	V
Logic Low input voltage	V <sub>IL</sub>	GND	-	0.3*IOVCC	V
Logic High input voltage	V <sub>IH</sub>	0.7*IOVCC	-	IOVCC	V
Logic Low output voltage	V <sub>OL</sub>	GND	-	0.2*IOVCC	V
Logic High output voltage	V <sub>OH</sub>	0.8*IOVCC	-	IOVCC	V
Current Consumption All White	lvcc	-	26	-	mA

# 5. Backlight Characteristic

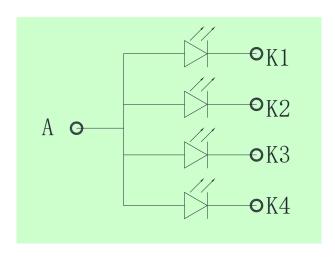
## 5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I <sub>F</sub> =20mA/LED	2.8	3.0	3.2	V
Forward Current	lF	Ta=25 °C, V <sub>F</sub> =3.0V/LED	-	80	-	mA
Power dissipation	Po	-	-	240	-	mW
Uniformity	Avg	-	80	-	-	%
LED working life(25°C)			-	30000	-	Hrs
Drive method		Constant co	urrent			
LED Configuration		4 White LEDs i	n parallel			

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25 $\pm2$  °C,60%RH $\pm5$ %, I<sub>F</sub>=20mA/LED.

## 5.2. Backlighting circuit



## 6. Optical Characteristics

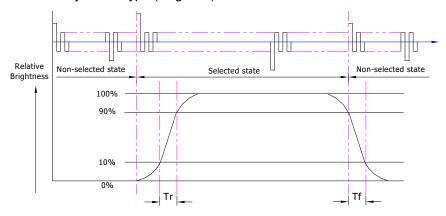
## 6.1. Optical Characteristics

Ta=25°C, VCI=3.3V, IOVCC=1.8V

	Item	•	Symbol	Condition	S	pecificati	on	Unit
	iten	l	Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminan	ce on						
	$TFT(I_f$ =20r	mA/LED)	Lv	Normally	320	400	-	cd/m²
de)	Contrast ratio	(See 6.3)	CR	viewing angle $\theta x = \phi y = 0^{\circ}$	1000	1500	-	
Backlight On (Transmissive Mode)	Response (See 6		TR+TF	θx – ψγ –υ°	1	30	35	ms
nis		Red	XR		0.574	0.624	0.674	
nsu		Red	YR		0.300	0.350	0.400	
T a	Chromoticity	Green	XG		0.286	0.336	0.386	
	Chromaticity Transmissive	Green	YG		0.559	0.609	0.659	
=	(See6.5)	Blue	Хв		0.083	0.133	0.183	
l jĝ	(0000.0)	blue	YB		0.060	0.110	0.160	
<mark>☆</mark>		White	Xw		0.281	0.331	0.381	
m		VVIIILE	Yw		0.329	0.379	0.429	
		Horizontol	θх+		75	85	ı	
	Viewing Angle	Horizontal	θх-	Center CR<10	75	85	-	Dog
	(See 6.4)	Vertical	фҮ+	Center CK 10	75	85	-	Deg.
		vertical	φY-		75	85		
	NTSC Ratio	(Gamut)			50	55.1	-	%

## 6.2. Definition of Response Time

### 6.2.1. Normally Black Type (Negative)

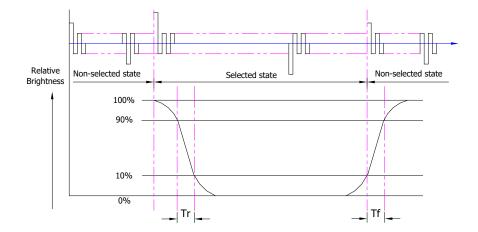


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

### 6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

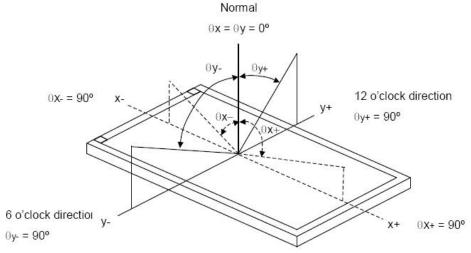
### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent		
Measuring Point Diameter	3mm//1mm		
Measuring Point Location	Active Area centre point		
Test nettern	A: All Pixels white		
Test pattern	B: All Pixel black		
Contrast setting	Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

### 6.4. Definition of Viewing Angles

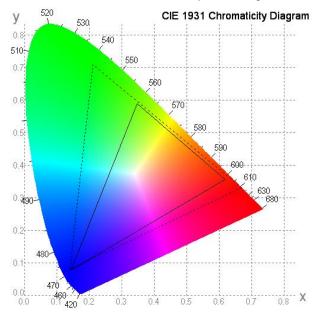


Measuring machine: LCD-5100 or EQUI

### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

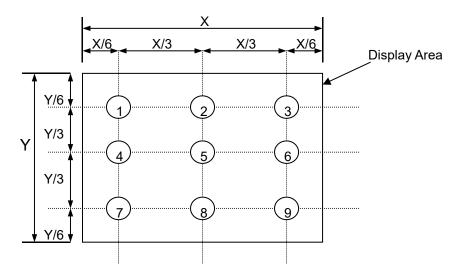


### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

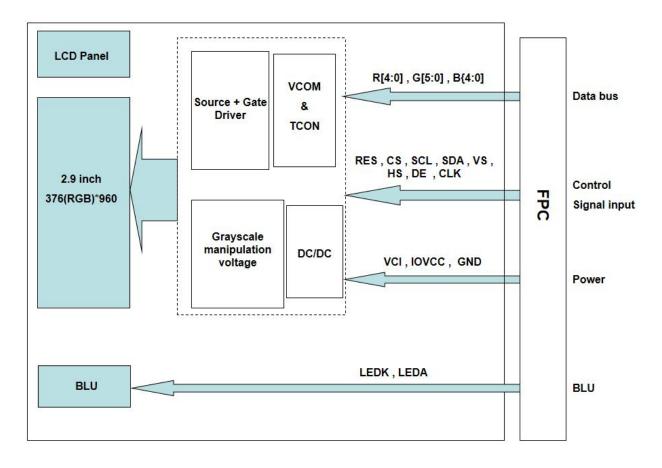
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2. Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



# 7. Block Diagram and Power Supply

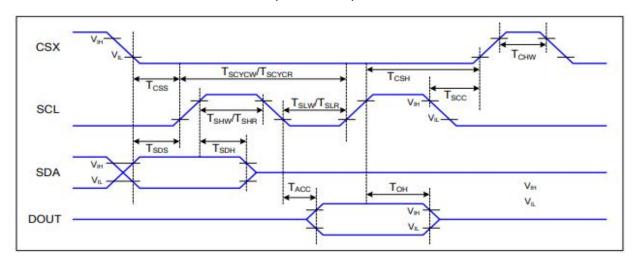


# 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	LEDA	Backlight anode.	
2	LEDK	Backlight cathode.	
3	GND	Ground.	
4	RES	Reset pin.	
5	VS	Vertical Sync Input.	
6	HS	Horizontal Sync Input.	
7	CLK	Sample clock.	
8	DE	Data Input Enable.	
9	GND	Ground.	
10	R4	Red data.	
11	R3	Red data.	
12	R2	Red data.	
13	R1	Red data.	
14	R0	Red data.	
15	G5	Green data.	
16	G4	Green data.	
17	G3	Green data.	
18	G2	Green data.	
19	G1	Green data.	
20	G0	Green data.	
21	B4	Blue data.	
22	В3	Blue data.	
23	B2	Blue data.	
24	B1	Blue data.	
25	В0	Blue data.	
26	IOVCC	Power Supply for I/O System.	
27	SDA	Serial data input.	
28	SCL	Serial clock.	
29	CS	Chip select signal.	
30	VCI	Power supply to the analog circuit.	
31	NC	No connect.	

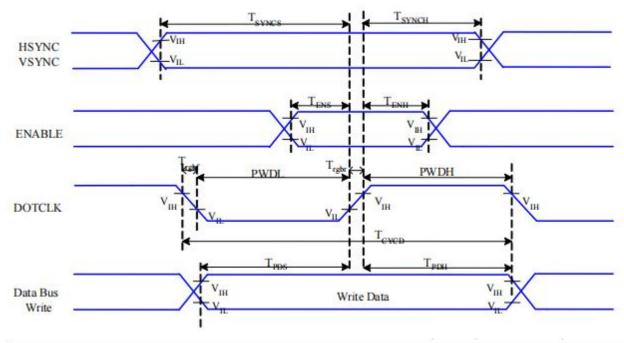
# 9. AC Characteristics

## 9.1. Serial Interface Characteristics (3-line serial):



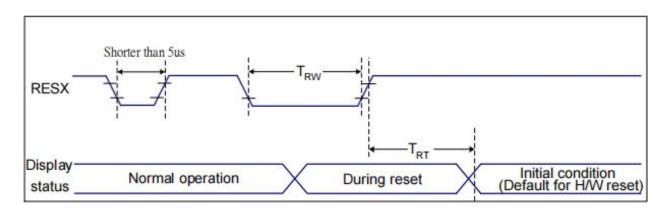
Signal	Symbol	Parameter	Min	Max	Unit	Description
	T <sub>CSS</sub>	Chip select setup time (write)	15	8	ns	
	T <sub>CSH</sub>	Chip select hold time (write)	15		ns	
CSX	Tcss	Chip select setup time (read)	60		ns	
	Tscc	Chip select hold time (read)	60		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
	Tscycw	Serial clock cycle (Write)	66		ns	
	TsHW	SCL "H" pulse width (Write)	15		ns	
SCL	T <sub>SLW</sub>	SCL "L" pulse width (Write)	15		ns	
SUL	T <sub>SCYCR</sub>	Serial clock cycle (Read)	150	8	ns	
	T <sub>SHR</sub>	SCL "H" pulse width (Read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (Read)	60		ns	
SDA	T <sub>SDS</sub>	Data setup time	10		ns	
(DIN)	Тѕрн	Data hold time	10		ns	

## 9.2. RGB Interface Characteristics



Signal Symbol Parameter		MIN	MAX	Unit	Description	
HSYNC, VSYNC	Tsyncs	T <sub>SYNCS</sub> VSYNC, HSYNC Setup Time		-	ns	
ENABLE	Tens	Enable Setup Time	5		ns	
	Tenn	Enable Hold Time	5	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	15	- 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1	ns	
	Тсуср	DOTCLK Cycle Time	33	- C	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	15	ns	
DB	TPDS	PD Data Setup Time	5	(50)	ns	
	Тррн	PD Data Hold Time	5	10.00	ns	

## 10. Reset Timing



Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT Deceted	-	5 (Note 1, 5)	ms	
	TRT	Reset cancel	90	120(Note 1, 6, 7)	ms

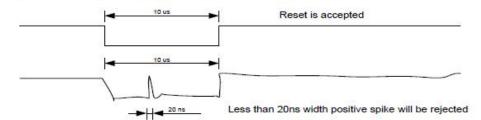
#### Note:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 42.

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9us	Reset starts	

Table 42 Reset Descript

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

## 11. Quality Assurance

#### 11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

### 11.3. Nonconforming Analysis & Disposition

- 11.3.1. Nonconforming analysis:
  - 11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 11.3.1.3. If can not finish the analysis on time, customer will be notified with the progress status.
- 11.3.2. Disposition of nonconforming:
  - 11.3.2.1. Non-conforming product over PPM level will be replaced.
  - 11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

#### 11.4. Agreement Items

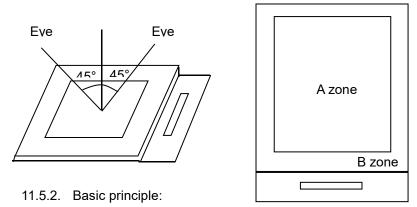
Shall negotiate with customer if the following situation occurs:

- 11.4.1. There is any discrepancy in standard of quality assurance.
- 11.4.2. Additional requirement to be added in product specification.
- 11.4.3. Any other special problem.

#### 11.5. Standard of the Product Visual Inspection

- 11.5.1. Appearance inspection:
  - 11.5.1.1. The inspection must be under illumination about  $1000 1500 \, lx$ , and the distance of view must be at  $30 \, cm \pm 2 \, cm$ .
  - 11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

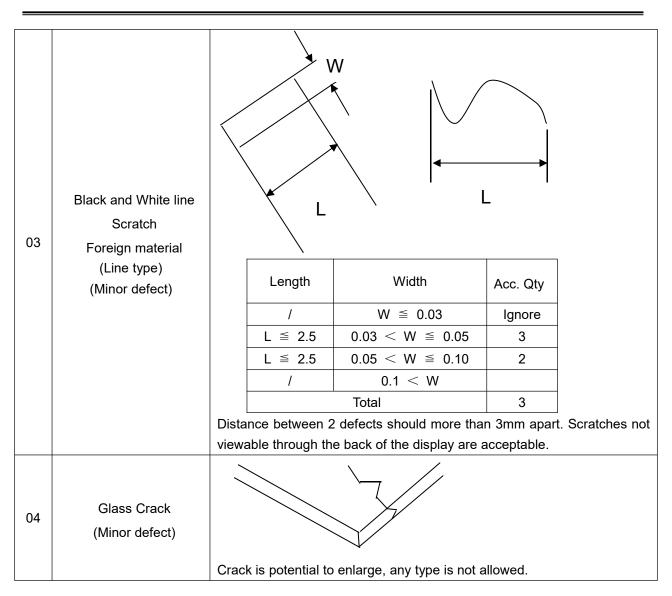


11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

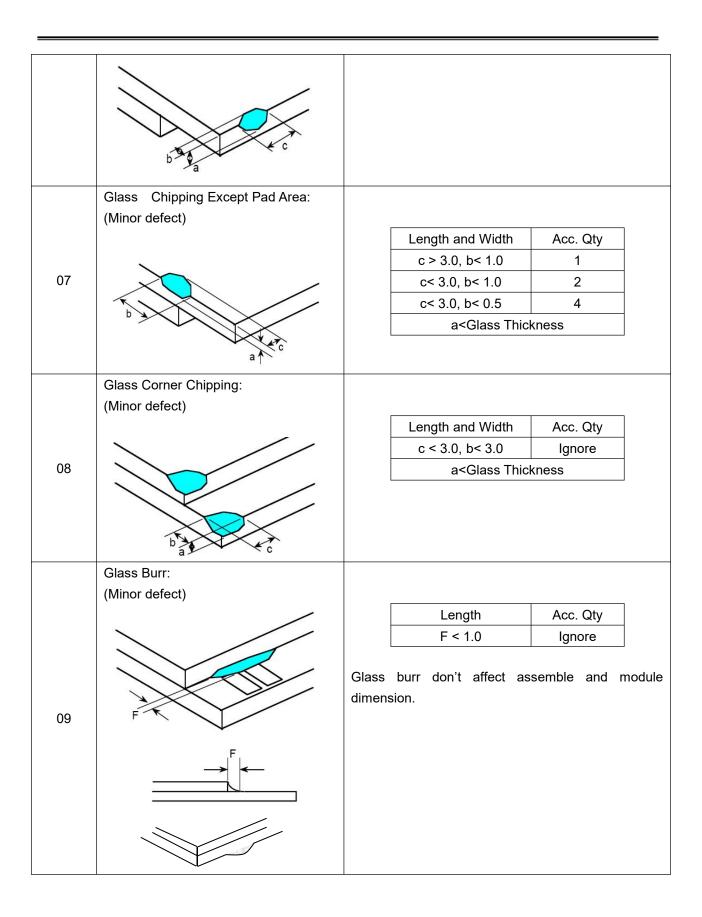
11.5.2.2. New item must be added on time when it is necessary.

## 11.6.Inspection Specification

No.	ltem	Criteria (Unit: mm)					
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b) /2  Distance between 2 defects sho		Area Size  φ≤0.10  0.10<φ≤0.15  0.15<φ≤0.25  0.25<φ  Total		Acc. Qty  Ignore  2  1  0  2 no include φ≤ 0.10	
02	Electrical Defect (Minor defect)	Display Area Total  Bright dot 0 0  Dark dot N≤2 N≤2  Total dot N≤2 N≤2  Mura Not visible through 5% ND fi  Remark:  1. Bright dot caused by scratch and foreign object			Note1 Note2 s to item 1.		



Glass Chipping Pad Area: (Minor defect)	Length and Width         Acc. Qty           c > 3.0, b< 1.0         1           c< 3.0, b< 1.0         3           a <glass td="" thickness<=""></glass>
Glass Chipping Rear of Pad Area: (Minor defect)	Length and Width       Acc. Qty         c > 3.0, b< 1.0



	T							
	FPC Defect:							
	(Minor defect)							
10	a:		10.1 Dent, pinhole	10.1 Dent, pinhole width a <w 3.<="" td=""></w>				
	,,,		(w: circuitry width.)	(w: circuitry width.)				
	a —		10.2 Open circuit is	10.2 Open circuit is unacceptable.				
			10.3 No oxidation, o	10.3 No oxidation, contamination and distortion.				
			Diameter	Acc. Qty	]			
	Bubble on		φ≤0.20	Ignore				
11	Polarizer		0.20 <φ≤0.30	4				
	(Minor defect)		0.30 <φ≤0.50	1				
	,		0.50 < φ	None				
			1	<u> </u>				
			Diameter	Acc. Qty	]			
	Dent on Polarizer		φ≤0.20	Ignore				
12			0.20 <φ≤0.30	4				
	(Minor defect)		0.30 <φ≤0.50	1				
			0.50 < φ	None				
	13.1 No rust, distortion on the Bezel.				J			
13	Bezel							
		13.2 No visible fingerprints, stains or other contamination.						
	PCB	14.1 No distortion or contamination on PCB terminals.						
14		14.2 All components on PCB must same as documented on the						
'.	. 52	BOM/component layout.						
		14.3 Follow IPC-A-600F.						
		<u> </u>						
15	Soldering	Follow IPC-A-610C standard						
	The below defeate assumble and total							
		The below defects must be rejected.						
		16.1 Missing vertical / horizontal segment,						
		16.2 Abnormal Display. 16.3 No function or no display.						
16	Electrical Defect		eds product specificatio	ne				
	(Major defect)			110.				
		16.5 LCD viewing angle defect.  16.6 No Backlight.						
		16.7 Dark Backlig						
		16.8 Touch Panel no function.						
	L	. c.c rodon i difei	no idilodon.					

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 11.7. Classification of Defects

- 11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2. Two minor defects are equal to one major in lot sampling inspection.

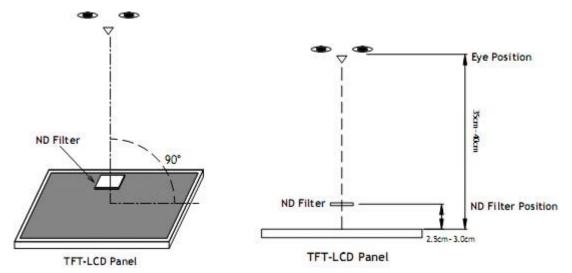
#### 11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 11.9. Packaging

- 11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2. Modules inside package box should have compliant mark.
- 11.9.3. All direct package materials shall offer ESD protection.

**Note1**: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min~ 70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
	Lieundai Static Discharge	Contact:±2KV 150pF/330 Ω 5 times		-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

## 13. Precautions and Warranty

#### 13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

#### 13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

#### 13.3.Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

#### 13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting

Solder Pin Lead

Recommended

Solder Pin Lead

Not Recommended

#### 13.4.2. Pins of EL

13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

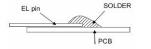
Typical Soldering Time: ≤2s

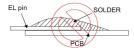
Minimum solder distance from EL lamp (body):2.0mm

13.4.2.4. No horizontal press on the EL leads during soldering.

13.4.2.5. 180° bend EL leads three times is not allowed.

#### 13.4.2.6. Solder Wetting





Recommended

Not Recommended

13.4.2.7. The type of the solder iron:





Recommended

Not Recommended

13.4.2.8. Solder Pad



#### 13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

#### 13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

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14	Pack	aging
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TBD

## 15. Outline Drawing

